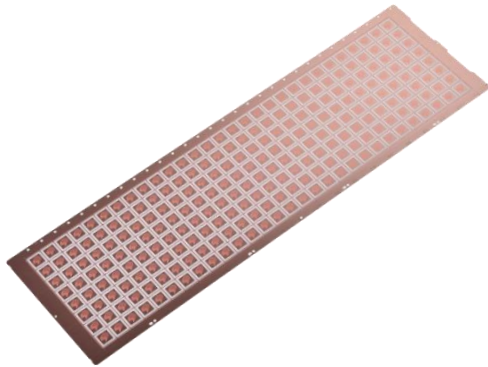


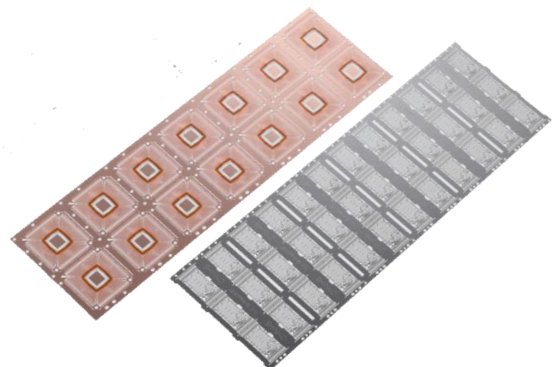
Leadframe

Features

SHINKO manufactures various types of leadframes using ultra-precision stamping or chemical etching.



Non-Lead Package (QFN) Leadframe



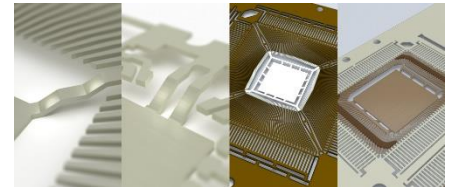
Leaded Package (QFP/TSOP) Leadframe

Technologies

■ Exposed Pad

Exposed pad leadframes are used to achieve high heat dissipation where the back side of a die-pad is exposed in a molded package.

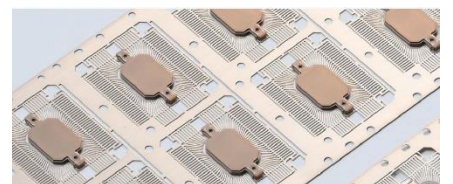
- Available with bending, half-cutting or half-etching at the edge of die-pad
- Various surface finishes : Ag plating, Pd plating and micro rough surface



Exposed Pad Leadframe

■ Riveting

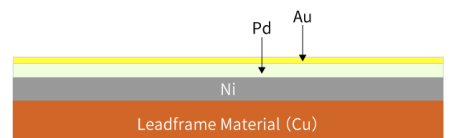
Riveting leadframe are two-layered leadframes stacking a non-die-pad leadframe and a heat slug by riveting technology used in high heat dissipating packages.



Riveting Leadframe

■ Pre-Plating

Pre-Plated leadframes reduce lead-time by eliminating external solder plating processes in IC assembly. SHINKO's Pd Pre-Plated leadframe (Pd P.P.F.) has three-layers (Nickel-Palladium-Gold) of plating on the entire leadframe surface to provide excellent interconnection.



Structure of Pd P.P.F.

